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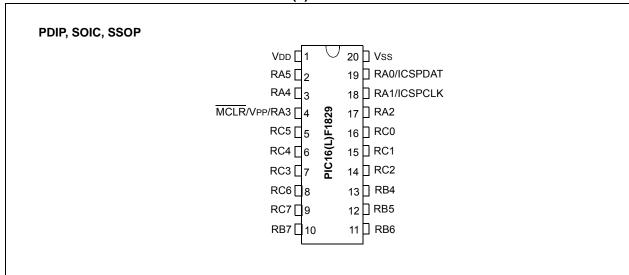
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I <sup>2</sup> C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-VFQFN Exposed Pad
Supplier Device Package	20-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1829-e-ml

FIGURE 3: 20-PIN DIAGRAM FOR PIC16(L)F1829





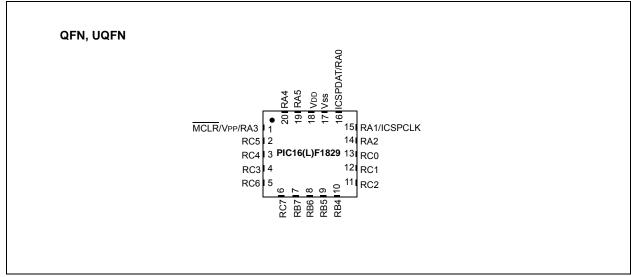


TABLE 1-3: PIC16(L)F1829 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RC2/AN6/CPS6/C12IN2-/	RC2	TTL	CMOS	General purpose I/O.
P1D <sup>(1,2)</sup> /P2B <sup>(1,2)</sup> /MDCIN1	AN6	AN	_	A/D Channel 6 input.
	CPS6	AN	_	Capacitive sensing input 6.
	C12IN2-	AN	_	Comparator C1 or C2 negative input.
	P1D	_	CMOS	PWM output.
	P2B	_	CMOS	PWM output.
	MDCIN1	ST	_	Modulator Carrier Input 1.
RC3/AN7/CPS7/C12IN3-/	RC3	TTL	CMOS	General purpose I/O.
P2A <sup>(1,2)</sup> /CCP2 <sup>(1,2)</sup> /P1C <sup>(1,2)</sup> /	AN7	AN	_	A/D Channel 7 input.
MDMIN	CPS7	AN	_	Capacitive sensing input 7.
	C12IN3-	AN	_	Comparator C1 or C2 negative input.
	P2A	_	CMOS	PWM output.
	CCP2	AN	_	Capture/Compare/PWM2.
	P1C	_	CMOS	PWM output.
	MDMIN	ST	_	Modulator source input.
RC4/C2OUT/SRNQ/P1B/TX <sup>(1)</sup> /	RC4	TTL	CMOS	General purpose I/O.
CK <sup>(1)</sup> /MDOUT	C2OUT	_	CMOS	Comparator C2 output.
	SRNQ	_	CMOS	SR Latch inverting output.
	P1B	_	CMOS	PWM output.
	TX	_	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
	MDOUT	_	CMOS	Modulator output.
RC5/P1A/CCP1/DT <sup>(1)</sup> /RX <sup>(1)</sup> /	RC5	TTL	CMOS	General purpose I/O.
MDCIN2	P1A	_	CMOS	PWM output.
	CCP1	ST	CMOS	Capture/Compare/PWM1.
	RX	ST	_	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
	MDCIN2	ST	_	Modulator Carrier Input 2.
RC6/AN8/CPS8/CCP4/SS1	RC6	TTL	CMOS	General purpose I/O.
	AN8	AN	_	A/D Channel 8 input.
	CPS8	AN	_	Capacitive sensing input 8.
	CCP4	AN	_	Capture/Compare/PWM4.
	SS1	ST	_	Slave Select input.
RC7/AN9/CPS9/SDO1	RC7	TTL	CMOS	General purpose I/O.
	AN9	AN	_	A/D Channel 9 input.
	CPS9	AN	_	Capacitive sensing input 9.
	SDO1	_	CMOS	SPI data output.
VDD	VDD	Power	_	Positive supply.
Vss	Vss	Power	_	Ground reference.

**Legend:** AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain

TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels  $I^2C^{TM}$  = Schmitt Trigger input with  $I^2C$  HV = High Voltage XTAL = Crystal levels

Note 1: Pin functions can be moved using the APFCON0 or APFCON1 register.

2: Default function location.

#### REGISTER 4-1: CONFIGURATION WORD 1

R/P-1/1	R/P-1/1	R/P-1/1	P-1/1 R/P-1/1 R/P-1/1		R/P-1/1
FCMEN	IESO	CLKOUTEN	BOREN<1:0>		CPD
bit 13					bit 8

R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1
CP	MCLRE	PWRTE	WDTE	E<1:0> FOSC<2:0			
bit 7							bit 0

Legend:

R = Readable bit P = Programmable bit U = Unimplemented bit, read as '1'
'0' = Bit is cleared '1' = Bit is set -n = Value when blank or after Bulk Erase

bit 13 FCMEN: Fail-Safe Clock Monitor Enable bit

1 = Fail-Safe Clock Monitor is enabled

0 = Fail-Safe Clock Monitor is disabled

bit 12 IESO: Internal External Switchover bit

1 = Internal/External Switchover mode is enabled

0 = Internal/External Switchover mode is disabled

bit 11 CLKOUTEN: Clock Out Enable bit

If FOSC configuration bits are set to LP, XT, HS modes:

This bit is ignored, CLKOUT function is disabled. Oscillator function on the CLKOUT pin.

All other FOSC modes:

1 = CLKOUT function is disabled. I/O function on the CLKOUT pin.

0 = CLKOUT function is enabled on the CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits<sup>(1)</sup>

11 = BOR enabled

10 = BOR enabled during operation and disabled in Sleep

01 = BOR controlled by SBOREN bit of the BORCON register

00 = BOR disabled

bit 8 CPD: Data Code Protection bit<sup>(2)</sup>

1 = Data memory code protection is disabled

0 = Data memory code protection is enabled

bit 7 CP: Code Protection bit<sup>(3)</sup>

1 = Program memory code protection is disabled

0 = Program memory code protection is enabled

bit 6 MCLRE: RA3/MCLR/VPP Pin Function Select bit

If LVP bit = 1:

This bit is ignored.

If LVP bit = 0:

1 =  $\overline{MCLR}/VPP$  pin function is  $\overline{MCLR}$ ; Weak pull-up enabled.

0 = MCLR/VPP pin function is digital input; MCLR internally disabled; Weak pull-up under control of WPUA register.

bit 5 **PWRTE**: Power-up Timer Enable bit<sup>(1)</sup>

1 = PWRT disabled

0 = PWRT enabled

bit 4-3 WDTE<1:0>: Watchdog Timer Enable bit

11 = WDT enabled

10 = WDT enabled while running and disabled in Sleep

01 = WDT controlled by the SWDTEN bit in the WDTCON register

00 = WDT disabled

Note 1: Enabling Brown-out Reset does not automatically enable Power-up Timer.

2: The entire data EEPROM will be erased when the code protection is turned off during an erase.

3: The entire program memory will be erased when the code protection is turned off.

## 8.6 Interrupt Control Registers

### 8.6.1 INTCON REGISTER

The INTCON register is a readable and writable register, that contains the various enable and flag bits for TMR0 register overflow, interrupt-on-change and external INT pin interrupts.

Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

#### REGISTER 8-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0/0	R-0/0						
GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF <sup>(1)</sup>
bit 7							bit 0

Note:

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7	GIE: Global Interrupt Enable bit
	1 = Enables all active interrupts
	0 = Disables all interrupts
bit 6	PEIE: Peripheral Interrupt Enable bit  1 = Enables all active peripheral interrupts  0 = Disables all peripheral interrupts
bit 5	<b>TMR0IE:</b> Timer0 Overflow Interrupt Enable bit 1 = Enables the Timer0 interrupt 0 = Disables the Timer0 interrupt
bit 4	INTE: INT External Interrupt Enable bit  1 = Enables the INT external interrupt  0 = Disables the INT external interrupt
bit 3	IOCIE: Interrupt-on-Change Enable bit  1 = Enables the interrupt-on-change  0 = Disables the interrupt-on-change
bit 2	<b>TMR0IF:</b> Timer0 Overflow Interrupt Flag bit 1 = TMR0 register has overflowed 0 = TMR0 register did not overflow
bit 1	INTF: INT External Interrupt Flag bit  1 = The INT external interrupt occurred  0 = The INT external interrupt did not occur
bit 0	IOCIF: Interrupt-on-Change Interrupt Flag bit <sup>(1)</sup> 1 = When at least one of the interrupt-on-change pins changed state  0 = None of the interrupt-on-change pins have changed state

**Note 1:** The IOCIF Flag bit is read-only and cleared when all the Interrupt-on-Change flags in the IOCxF register have been cleared by software.

### REGISTER 11-6: EECON2: EEPROM CONTROL 2 REGISTER

W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0
			EEPROM Cor	ntrol Register 2	!		
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

S = Bit can only be set x = Bit is unknown -n/n = Value at POR and BOR/Value at all other Resets

'1' = Bit is set '0' = Bit is cleared

#### bit 7-0 Data EEPROM Unlock Pattern bits

To unlock writes, a 55h must be written first, followed by an AAh, before setting the WR bit of the EECON1 register. The value written to this register is used to unlock the writes. There are specific timing requirements on these writes. Refer to **Section 11.2.2 "Writing to the Data EEPROM Memory"** for more information.

TABLE 11-3: SUMMARY OF REGISTERS ASSOCIATED WITH DATA EEPROM

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page	
EECON1	EEPGD	CFGS	LWLO	FREE	WRERR	WREN	WR	RD	114	
EECON2	EEPROM Control Register 2 (not a physical register)									
EEADRL				EEADF	RL<7:0>				113	
EEADRH	(1)									
EEDATL				EEDAT	ΓL<7:0>				113	
EEDATH	_	_			EEDAT	H<5:0>			113	
INTCON	GIE	PEIE	TMR0IE INTE IOCIE TMR0IF INTF IOCIF						87	
PIE2	OSFIE	C2IE	C1IE	EEIE	BCL1IE	_	_	CCP2IE	89	
PIR2	OSFIF	C2IF	C1IF	EEIF	BCL1IF	_	_	CCP2IF	93	

**Legend:** — Unimplemented location, read as '0'. Shaded cells are not used by data EEPROM module.

Note 1: Unimplemented, read as '1'.

<sup>\*</sup> Page provides register information.

#### 12.0 I/O PORTS

Depending on the device selected and peripherals enabled, there are up to two ports available. In general, when a peripheral is enabled on a port pin, that pin cannot be used as a general purpose output. However, the pin can still be read.

Each port has three standard registers for its operation. These registers are:

- TRISx registers (data direction)
- PORTx registers (reads the levels on the pins of the device)
- LATx registers (output latch)

Some ports may have one or more of the following additional registers. These registers are:

- ANSELx (analog select)
- WPUx (weak pull-up)
- · INLVLx (input level control)

TABLE 12-1: PORT AVAILABILITY PER DEVICE

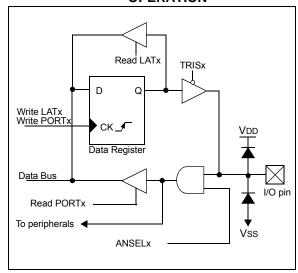
Device	PORTA	PORTB	PORTC
PIC16(L)F1825	•		•
PIC16(L)F1829	•	•	•

The Data Latch (LATx registers) is useful for read-modify-write operations on the value that the I/O pins are driving.

A write operation to the LATx register has the same effect as a write to the corresponding PORTx register. A read of the LATx register reads of the values held in the I/O PORT latches, while a read of the PORTx register reads the actual I/O pin value.

Ports that support analog inputs have an associated ANSELx register. When an ANSEL bit is set, the digital input buffer associated with that bit is disabled. Disabling the input buffer prevents analog signal levels on the pin between a logic high and low from causing excessive current in the logic input circuitry. A simplified model of a generic I/O port, without the interfaces to other peripherals, is shown in Figure 12-1.

## FIGURE 12-1: GENERIC I/O PORT OPERATION



#### **EXAMPLE 12-1: INITIALIZING PORTA**

```
; This code example illustrates
; initializing the PORTA register. The
; other ports are initialized in the same
; manner.
BANKSEL PORTA
CLRF
        PORTA
                     ;Init PORTA
BANKSEL LATA
                     ;Data Latch
CLRF
        T.ATA
BANKSEL ANSELA
                     ;digital I/O
CLRF
        ANSELA
BANKSEL TRISA
        B'00111000'
MOVLW
                    ;Set RA<5:3> as inputs
MOVWF
                     ;and set RA<2:0> as
        TRISA
                     ;outputs
```

### 17.4 Low-Power Voltage State

In order for the DAC module to consume the least amount of power, one of the two voltage reference input sources to the resistor ladder must be disconnected. Either the positive voltage source, (VSOURCE+), or the negative voltage source, (VSOURCE-) can be disabled.

The negative voltage source is disabled by setting the DACLPS bit in the DACCON0 register. Clearing the DACLPS bit in the DACCON0 register disables the positive voltage source.

# 17.4.1 OUTPUT CLAMPED TO POSITIVE VOLTAGE SOURCE

The DAC output voltage can be set to VSOURCE+ with the least amount of power consumption by performing the following:

- Clearing the DACEN bit in the DACCON0 register.
- Setting the DACLPS bit in the DACCON0 register.
- Configuring the DACPSS bits to the proper positive source.
- Configuring the DACR<4:0> bits to '11111' in the DACCON1 register.

This is also the method used to output the voltage level from the FVR to an output pin. See **Section 17.5** "**Operation During Sleep**" for more information.

Reference Figure 17-3 for output clamping examples.

# 17.4.2 OUTPUT CLAMPED TO NEGATIVE VOLTAGE SOURCE

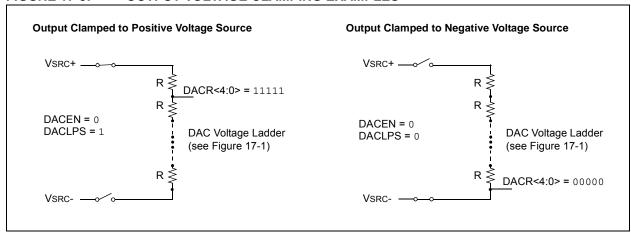
The DAC output voltage can be set to VSOURCE- with the least amount of power consumption by performing the following:

- · Clearing the DACEN bit in the DACCON0 register.
- Clearing the DACLPS bit in the DACCON0 register.
- Configuring the DACNSS bits to the proper negative source.
- Configuring the DACR<4:0> bits to '00000' in the DACCON1 register.

This allows the comparator to detect a zero-crossing while not consuming additional current through the DAC module.

Reference Figure 17-3 for output clamping examples.

### FIGURE 17-3: OUTPUT VOLTAGE CLAMPING EXAMPLES



### 17.5 Operation During Sleep

When the device wakes up from Sleep through an interrupt or a Watchdog Timer time-out, the contents of the DACCON0 register are not affected. To minimize current consumption in Sleep mode, the voltage reference should be disabled.

#### 17.6 Effects of a Reset

A device Reset affects the following:

- · DAC is disabled.
- DAC output voltage is removed from the DACOUT pin.
- The DACR<4:0> range select bits are cleared.

#### 24.2.5 COMPARE DURING SLEEP

The Compare mode is dependent upon the system clock (Fosc) for proper operation. Since Fosc is shut down during Sleep mode, the Compare mode will not function properly during Sleep.

#### 24.2.6 ALTERNATE PIN LOCATIONS

This module incorporates I/O pins that can be moved to other locations with the use of the alternate pin function registers, APFCON0 and APFCON1. To determine which pins can be moved and what their default locations are upon a Reset, see Section 12.1 "Alternate Pin Function" for more information.

**TABLE 24-4:** SUMMARY OF REGISTERS ASSOCIATED WITH COMPARE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
APFCON1	_	_	SDO2SEL <sup>(2)</sup>	SS2SEL <sup>(2)</sup>	P1DSEL	P1CSEL	P2BSEL	CCP2SEL	119
CCP1CON	P1M<	1:0> <sup>(1)</sup>	DC1B	<1:0>		CCP1M<	:3:0>		224
CCP2CON	P2M<	1:0> <sup>(1)</sup>	DC2B	<1:0>		CCP2M<	:3:0>		224
CCP3CON	_	_	DC3B	<1:0>		CCP3M<	:3:0>		224
CCP4CON	_	_	DC4B	<1:0>		CCP4M<	:3:0>		224
CCPRxL	Capture/Com	pare/PWM Reg	gister x Low By	te (LSB)					202*
CCPRxH	Capture/Com	pare/PWM Rec	gister x High By	yte (MSB)					202*
INLVLA	_	_	INLVLA5	INLVLA4	INLVLA3	INLVLA2	INLVLA1	INLVLA0	124
INLVLC	INLVLC7 <sup>(2)</sup>	INLVLC6 <sup>(2)</sup>	INLVLC5	INLVLC4	INLVLC3	INLVLC2	INLVLC1	INLVLC0	135
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	87
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	88
PIE2	OSFIE	C2IE	C1IE	EEIE	BCL1IE	ı	_	CCP2IE	89
PIE3		_	CCP4IE	CCP3IE	TMR6IE	1	TMR4IE	_	90
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	92
PIR2	OSFIF	C2IF	C1IF	EEIF	BCL1IF	ı	_	CCP2IF	93
PIR3		_	CCP4IF	CCP3IF	TMR6IF	1	TMR4IF	_	94
T1CON	TMR10	S<1:0>	T1CKP	S<1:0>	T10SCEN	T1SYNC	_	TMR10N	185
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/DONE	T1GVAL	T1GS	S<1:0>	186
TMR1L	Holding Regis	ster for the Lea	st Significant B	syte of the 16-b	oit TMR1 Register	•		•	181*
TMR1H	Holding Regis	ster for the Mos	st Significant B	yte of the 16-b	it TMR1 Register				181*
TRISA	_	_	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	122
TRISC	TRISC7 <sup>(2)</sup>	TRISC6 <sup>(2)</sup>	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	133

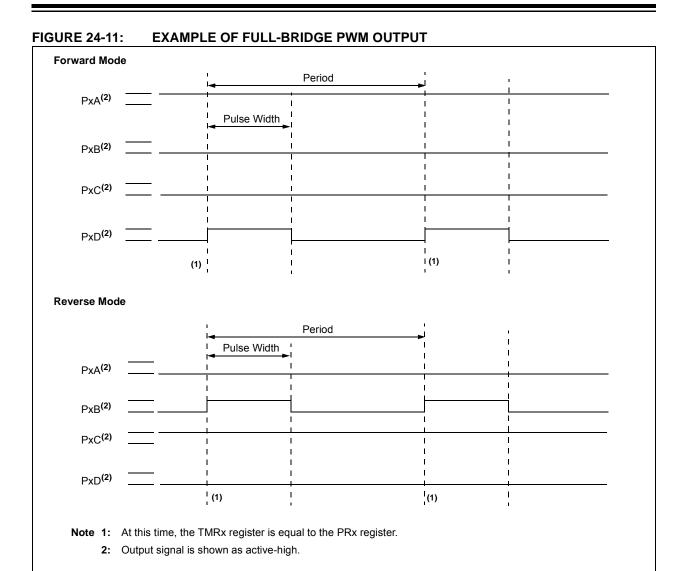
**Legend:** — Unimplemented location, read as '0'. Shaded cells are not used by Compare mode.

Applies to ECCP modules only. PIC16(L)F1829 only. PIC16(L)F1825 only. Note 1:

2:

3:

<sup>\*</sup> Page provides register information.

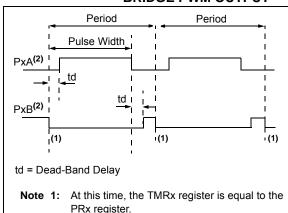


## 24.4.5 PROGRAMMABLE DEAD-BAND DELAY MODE

In Half-Bridge applications where all power switches are modulated at the PWM frequency, the power switches normally require more time to turn off than to turn on. If both the upper and lower power switches are switched at the same time (one turned on, and the other turned off), both switches may be on for a short period of time until one switch completely turns off. During this brief interval, a very high current (*shootthrough current*) will flow through both power switches, shorting the bridge supply. To avoid this potentially destructive shoot-through current from flowing during switching, turning on either of the power switches is normally delayed to allow the other switch to completely turn off.

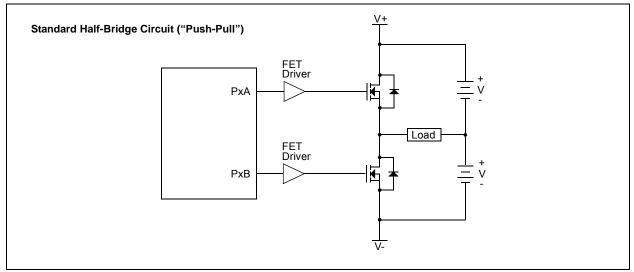
In Half-Bridge mode, a digitally programmable deadband delay is available to avoid shoot-through current from destroying the bridge power switches. The delay occurs at the signal transition from the non-active state to the active state. See Figure 24-16 for illustration. The lower seven bits of the associated PWMxCON register (Register 24-4) sets the delay period in terms of microcontroller instruction cycles (Tcy or 4 Tosc).

### FIGURE 24-16: EXAMPLE OF HALF-BRIDGE PWM OUTPUT



2: Output signals are shown as active-high.

#### FIGURE 24-17: EXAMPLE OF HALF-BRIDGE APPLICATIONS



### 25.3 I<sup>2</sup>C MODE OVERVIEW

The Inter-Integrated Circuit Bus (I²C) is a multi-master serial data communication bus. Devices communicate in a master/slave environment where the master devices initiate the communication. A Slave device is controlled through addressing.

The I<sup>2</sup>C bus specifies two signal connections:

- · Serial Clock (SCLx)
- Serial Data (SDAx)

Figure 25-11 shows the block diagram of the MSSPx module when operating in I<sup>2</sup>C mode.

Both the SCLx and SDAx connections are bidirectional open-drain lines, each requiring pull-up resistors for the supply voltage. Pulling the line to ground is considered a logical zero and letting the line float is considered a logical one.

Figure 25-11 shows a typical connection between two processors configured as master and slave devices.

The I<sup>2</sup>C bus can operate with one or more master devices and one or more slave devices.

There are four potential modes of operation for a given device:

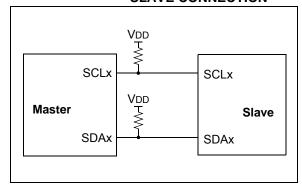
- Master Transmit mode (master is transmitting data to a slave)
- Master Receive mode (master is receiving data from a slave)
- Slave Transmit mode (slave is transmitting data to a master)
- Slave Receive mode (slave is receiving data from the master)

To begin communication, a master device starts out in Master Transmit mode. The master device sends out a Start bit followed by the address byte of the slave it intends to communicate with. This is followed by a single Read/Write bit, which determines whether the master intends to transmit to or receive data from the slave device.

If the requested slave exists on the bus, it will respond with an Acknowledge bit, otherwise known as an ACK. The master then continues in either Transmit mode or Receive mode and the slave continues in the complement, either in Receive mode or Transmit mode, respectively.

A Start bit is indicated by a high-to-low transition of the SDAx line while the SCLx line is held high. Address and data bytes are sent out, Most Significant bit (MSb) first. The Read/Write bit is sent out as a logical one when the master intends to read data from the slave, and is sent out as a logical zero when it intends to write data to the slave.

FIGURE 25-11: I<sup>2</sup>C MASTER/ SLAVE CONNECTION



The Acknowledge bit (ACK) is an active-low signal, which holds the SDAx line low to indicate to the transmitter that the slave device has received the transmitted data and is ready to receive more.

The transition of a data bit is always performed while the SCLx line is held low. Transitions that occur while the SCLx line is held high are used to indicate Start and Stop bits.

If the master intends to write to the slave, then it repeatedly sends out a byte of data, with the slave responding after each byte with an ACK bit. In this example, the master device is in Master Transmit mode and the slave is in Slave Receive mode.

If the master intends to read from the slave, then it repeatedly receives a byte of data from the slave, and responds after each byte with an  $\overline{\text{ACK}}$  bit. In this example, the master device is in Master Receive mode and the slave is Slave Transmit mode.

On the last byte of data communicated, the master device may end the transmission by sending a Stop bit. If the master device is in Receive mode, it sends the Stop bit in place of the last  $\overline{ACK}$  bit. A Stop bit is indicated by a low-to-high transition of the SDAx line while the SCLx line is held high.

In some cases, the master may want to maintain control of the bus and re-initiate another transmission. If so, the master device may send another Start bit in place of the Stop bit or last ACK bit when it is in receive mode.

The I<sup>2</sup>C bus specifies three message protocols;

- Single message where a master writes data to a slave.
- Single message where a master reads data from a slave.
- Combined message where a master initiates a minimum of two writes, or two reads, or a combination of writes and reads, to one or more slaves.

### 25.6 I<sup>2</sup>C MASTER MODE

Master mode is enabled by setting and clearing the appropriate SSPM bits in the SSPxCON1 register and by setting the SSPEN bit. In Master mode, the SDAx and SCKx pins must be configured as inputs. The MSSP peripheral hardware will override the output driver TRIS controls when necessary to drive the pins low.

Master mode of operation is supported by interrupt generation on the detection of the Start and Stop conditions. The Stop (P) and Start (S) bits are cleared from a Reset or when the MSSPx module is disabled. Control of the  $I^2C$  bus may be taken when the P bit is set, or the bus is Idle.

In Firmware Controlled Master mode, user code conducts all I<sup>2</sup>C bus operations based on Start and Stop bit condition detection. Start and Stop condition detection is the only active circuitry in this mode. All other communication is done by the user software directly manipulating the SDAx and SCLx lines.

The following events will cause the SSPx Interrupt Flag bit, SSPxIF, to be set (SSPx interrupt, if enabled):

- · Start condition detected
- · Stop condition detected
- · Data transfer byte transmitted/received
- · Acknowledge transmitted/received
- · Repeated Start generated
  - Note 1: The MSSPx module, when configured in I<sup>2</sup>C Master mode, does not allow queuing of events. For instance, the user is not allowed to initiate a Start condition and immediately write the SSPxBUF register to initiate transmission before the Start condition is complete. In this case, the SSPxBUF will not be written to and the WCOL bit will be set, indicating that a write to the SSPxBUF did not occur
    - 2: When in Master mode, Start/Stop detection is masked and an interrupt is generated when the SEN/PEN bit is cleared and the generation is complete.

### 25.6.1 I<sup>2</sup>C MASTER MODE OPERATION

The master device generates all of the serial clock pulses and the Start and Stop conditions. A transfer is ended with a Stop condition or with a Repeated Start condition. Since the Repeated Start condition is also the beginning of the next serial transfer, the I<sup>2</sup>C bus will not be released.

In Master Transmitter mode, serial data is output through SDAx, while SCLx outputs the serial clock. The first byte transmitted contains the slave <u>address of</u> the receiving device (7 bits) and the Read/Write (R/W) bit. In this case, the R/W bit will be logic '0'. Serial data is transmitted eight bits at a time. After each byte is transmitted, an Acknowledge bit is received. Start and Stop conditions are output to indicate the beginning and the end of a serial transfer.

In Master Receive mode, the first byte transmitted contains the slave address of the transmitting device (7 bits) and the R/W bit. In this case, the R/W bit will be logic '1'. Thus, the first byte transmitted is a 7-bit slave address followed by a '1' to indicate the receive bit. Serial data is received via SDAx, while SCLx outputs the serial clock. Serial data is received eight bits at a time. After each byte is received, an Acknowledge bit is transmitted. Start and Stop conditions indicate the beginning and end of transmission.

A Baud Rate Generator is used to set the clock frequency output on SCLx. See **Section 25.7 "Baud Rate Generator"** for more detail.

#### 26.3.4 BREAK CHARACTER SEQUENCE

The EUSART module has the capability of sending the special Break character sequences that are required by the LIN bus standard. A Break character consists of a Start bit, followed by 12 '0' bits and a Stop bit.

To send a Break character, set the SENDB and TXEN bits of the TXSTA register. The Break character transmission is then initiated by a write to the TXREG. The value of data written to TXREG will be ignored and all '0's will be transmitted.

The SENDB bit is automatically reset by hardware after the corresponding Stop bit is sent. This allows the user to preload the transmit FIFO with the next transmit byte following the Break character (typically, the Sync character in the LIN specification).

The TRMT bit of the TXSTA register indicates when the transmit operation is active or Idle, just as it does during normal transmission. See Figure 26-9 for the timing of the Break character sequence.

#### 26.3.4.1 Break and Sync Transmit Sequence

The following sequence will start a message frame header made up of a Break, followed by an auto-baud Sync byte. This sequence is typical of a LIN bus master.

- 1. Configure the EUSART for the desired mode.
- 2. Set the TXEN and SENDB bits to enable the Break sequence.
- Load the TXREG with a dummy character to initiate transmission (the value is ignored).
- Write '55h' to TXREG to load the Sync character into the transmit FIFO buffer.
- After the Break has been sent, the SENDB bit is reset by hardware and the Sync character is then transmitted.

When the TXREG becomes empty, as indicated by the TXIF, the next data byte can be written to TXREG.

#### 26.3.5 RECEIVING A BREAK CHARACTER

The Enhanced EUSART module can receive a Break character in two ways.

The first method to detect a Break character uses the FERR bit of the RCSTA register and the Received data as indicated by RCREG. The Baud Rate Generator is assumed to have been initialized to the expected baud

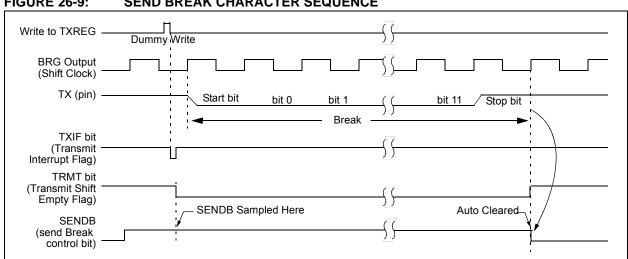
A Break character has been received when;

- · RCIF bit is set
- · FERR bit is set
- RCREG = 00h

The second method uses the Auto-Wake-up feature described in Section 26.3.3 "Auto-Wake-up on Break". By enabling this feature, the EUSART will sample the next two transitions on RX/DT, cause an RCIF interrupt, and receive the next data byte followed by another interrupt.

Note that following a Break character, the user will typically want to enable the Auto-Baud Detect feature. For both methods, the user can set the ABDEN bit of the BAUDCON register before placing the EUSART in Sleep mode.





#### REGISTER 27-1: CPSCON0: CAPACITIVE SENSING CONTROL REGISTER 0

R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0	R-0/0	R/W-0/0
CPSON	CPSRM	_	_	CPSRN	NG<1:0>	CPSOUT	T0XCS
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

u = Bit is unchanged x = Bit is unknown -n/n = Value at POR and BOR/Value at all other Resets

'1' = Bit is set '0' = Bit is cleared

bit 7 CPSON: Capacitive Sensing Module Enable bit

1 = CPS module is enabled 0 = CPS module is disabled

bit 6 CPSRM: Capacitive Sensing Reference Mode bit

1 = Capacitive Sensing module is in Variable Voltage Reference mode.

0 = Capacitive Sensing module is in Fixed Voltage Reference mode..

bit 5-4 Unimplemented: Read as '0'

bit 3-2 CPSRNG<1:0>: Capacitive Sensing Current Range bits

If CPSRM = 0 (Fixed Voltage Reference mode):

00 = Oscillator is off

01 = Oscillator is in low range

10 = Oscillator is in medium range

11 = Oscillator is in high range

#### If CPSRM = 1 (Variable Voltage Reference mode):

00 = Oscillator is on. Noise Detection mode. No Charge/Discharge current is supplied.

01 = Oscillator is in low range

10 = Oscillator is in medium range

11 = Oscillator is in high range

bit 1 CPSOUT: Capacitive Sensing Oscillator Status bit

1 = Oscillator is sourcing current (Current flowing out of the pin)

0 = Oscillator is sinking current (Current flowing into the pin)

bit 0 TOXCS: Timer0 External Clock Source Select bit

If TMR0CS = 1:

The T0XCS bit controls which clock external to the core/Timer0 module supplies Timer0:

1 = Timer0 clock source is the capacitive sensing oscillator

0 = Timer0 clock source is the T0CKI pin

If TMR0CS = 0:

Timer0 clock source is controlled by the core/Timer0 module and is Fosc/4

MOVWI	Move W to INDFn
Syntax:	[ label ] MOVWI ++FSRn [ label ] MOVWIFSRn [ label ] MOVWI FSRn++ [ label ] MOVWI FSRn [ label ] MOVWI k[FSRn]
Operands:	$\begin{split} &n \in [0,1] \\ &mm \in [00,01,10,11] \\ &-32 \le k \le 31 \end{split}$
Operation:	<ul> <li>W → INDFn</li> <li>Effective address is determined by</li> <li>FSR + 1 (preincrement)</li> <li>FSR - 1 (predecrement)</li> <li>FSR + k (relative offset)</li> <li>After the Move, the FSR value will be either:</li> <li>FSR + 1 (all increments)</li> <li>FSR - 1 (all decrements)</li> <li>Unchanged</li> </ul>
Status Affected:	None

Mode	Syntax	mm
Preincrement	++FSRn	00
Predecrement	FSRn	01
Postincrement	FSRn++	10
Postdecrement	FSRn	11

Description:

This instruction is used to move data between W and one of the indirect registers (INDFn). Before/after this move, the pointer (FSRn) is updated by pre/post incrementing/decrementing it.

Note: The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the FSRn.

FSRn is limited to the range 0000h - FFFFh. Incrementing/decrementing it beyond these bounds will cause it to wrap-around.

The increment/decrement operation on FSRn WILL NOT affect any Status bits.

NOP	No Operation
Syntax:	[ label ] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.
Words:	1
Cycles:	1
Example:	NOP
OPTION	Load OPTION_REG Register
OPTION	Load OPTION_REG Register with W
Syntax:	[ label ] OPTION
Operands:	None
Operation:	(W) $\rightarrow$ OPTION REG
Status Affected:	(W) → OF HON_REG  None
olulus Alleoled.	Move data from W register to
Description:	
Description:	OPTION_REG register.
·	· ·
Words:	OPTION_REG register.
Description:  Words: Cycles: Example:	OPTION_REG register.
Words:	OPTION_REG register.  1 1
Words: Cycles:	OPTION_REG register.  1 1 OPTION Before Instruction OPTION_REG = 0xFF
Words: Cycles:	OPTION_REG register.  1 1 OPTION Before Instruction

RESET	Software Reset
Syntax:	[label] RESET
Operands:	None
Operation:	Execute a device Reset. Resets the nRI flag of the PCON register.
Status Affected:	None
Description:	This instruction provides a way to execute a hardware Reset by software.

## 30.5 Memory Programming Requirements

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +125^{\circ}\text{C}$					
Param No.	Sym.	Characteristic Min. Typ† Max. Unit		Units	Conditions		
		Program Memory High Voltage Programming Specifications					
D110	VIHH	Voltage on MCLR/VPP/RA5 pin	8.0	_	9.0	V	(Note 3, 4)
D111	IDDVPP	Programming/Erase Current on VPP, High Voltage Programming	_	_	10	mA	
D112	VBE	VDD for Bulk Erase	2.7	_	VDDMAX	V	
D113	VPEW	VDD for Write or Row Erase	VDDMIN	_	VDDMAX	V	
D114	IPPPGM	Programming/Erase Current on VPP, Low Voltage Programming	_	1.0	_	mA	
D115	IDDPGM	Programming/Erase Current on VDD, High or Low Voltage Programming	_	5.0	_	mA	
		Data EEPROM Memory					
D116	ED	Byte Endurance	100K	_	_	E/W	-40°C to +85°C
D117	VDRW	VDD for Read/Write	VDDMIN	_	VDDMAX	V	
D118	TDEW	Erase/Write Cycle Time	_	4.0	5.0	ms	
D119	TRETD	Characteristic Retention	_	40	_	Year	Provided no other specifications are violated
D120	TREF	Number of Total Erase/Write Cycles before Refresh <sup>(2)</sup>	1M	10M	_	E/W	-40°C to +85°C
		Program Flash Memory					
D121	EР	Cell Endurance	10K	_	_	E/W	-40°C to +85°C ( <b>Note 1</b> )
D122	VPRW	VDD for Read/Write	VDDMIN	_	VDDMAX	V	
D123	Tıw	Self-timed Write Cycle Time	_	2	2.5	ms	
D124	TRETD	Characteristic Retention	_	40	_	Year	Provided no other specifications are violated

<sup>†</sup> Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1: Self-write and Block Erase.
  - 2: Refer to Section 11.2 "Using the Data EEPROM" for a more detailed discussion on data EEPROM endurance.
  - **3:** Required only if single-supply programming is disabled.
  - 4: The MPLAB ICD 2 does not support variable VPP output. Circuitry to limit the MPLAB ICD 2 VPP voltage must be placed between the MPLAB ICD 2 and target system when programming or debugging with the MPLAB ICD 2.



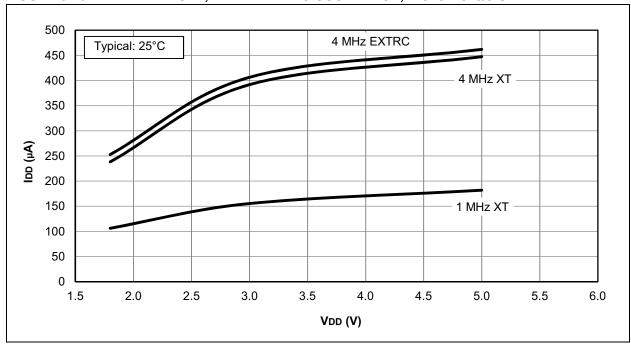
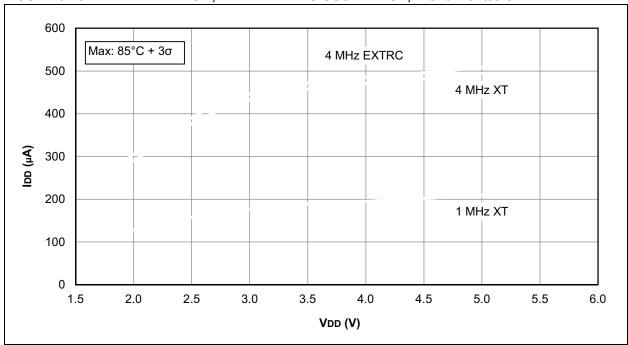
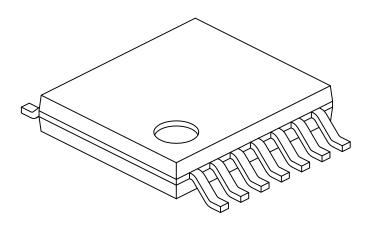


FIGURE 31-6: IDD MAXIMUM, XT AND EXTRC OSCILLATOR, PIC16F1825/9 ONLY



## 14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX	
Number of Pins	14				
Pitch	е		0.65 BSC		
Overall Height	Α	-	-	1.20	
Molded Package Thickness	A2	0.80	1.00	1.05	
Standoff	A1	0.05	-	0.15	
Overall Width	E	6.40 BSC			
Molded Package Width	E1	4.30 4.40 4.50			
Molded Package Length	D	4.90 5.00 5.10			
Foot Length	L	0.45	0.60	0.75	
Footprint	(L1)	1.00 REF			
Foot Angle	$\varphi$	0°	-	8°	
Lead Thickness	С	0.09		0.20	
Lead Width	b	0.19	-	0.30	

#### Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- 3. Dimensioning and tolerancing per ASME Y14.5M

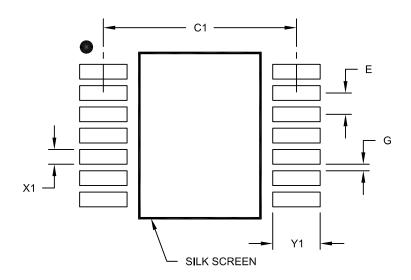
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-087C Sheet 2 of 2

## 14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS				
Dimension	MIN	NOM	MAX		
Contact Pitch	E	0.65 BSC			
Contact Pad Spacing	C1		5.90		
Contact Pad Width (X14)	X1			0.45	
Contact Pad Length (X14)	Y1			1.45	
Distance Between Pads	G	0.20			

#### Notes:

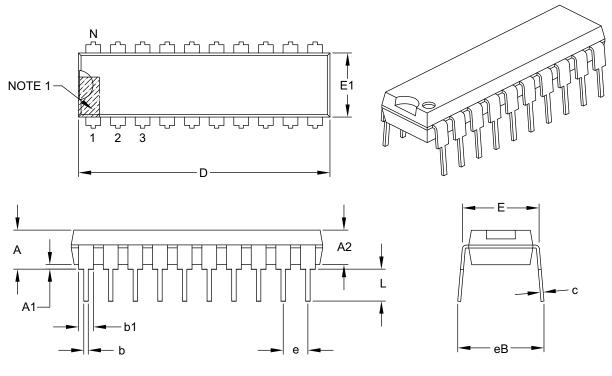
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2087A

## 20-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	INCHES				
Di	Dimension Limits		NOM	MAX	
Number of Pins	N	20			
Pitch	е	.100 BSC			
Top to Seating Plane	А	_	_	.210	
Molded Package Thickness	A2	.115	.130	.195	
Base to Seating Plane	A1	.015	_	_	
Shoulder to Shoulder Width	E	.300	.310	.325	
Molded Package Width	E1	.240	.250	.280	
Overall Length	D	.980	1.030	1.060	
Tip to Seating Plane	L	.115	.130	.150	
Lead Thickness	С	.008	.010	.015	
Upper Lead Width	b1	.045	.060	.070	
Lower Lead Width	b	.014	.018	.022	
Overall Row Spacing §	eB	_	_	.430	

#### Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic.
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-019B